1. Record Nr. UNINA9910404075003321

Autore	Beyes Timon
Titolo	Organize / / Timon Beyes [and four others]
Pubbl/distr/stampa	Mannheim : , : Meson press, , 2019
Descrizione fisica	1 online resource (103 pages)
Collana	In Search of Media
Disciplina	302.23
Soggetti	Mass media - Social aspects
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Nota di contenuto	Series Foreword vii -- Introduction ix -- Timon Beyes, Lisa Conrad, and Reinhoid Martin -- [1] Media Organize: Persons Reinhoid Martin 1 -- [2] Organizing Media: Security and Entertainment Timon Beyes 29 -- [3] Organization Is the Message: Gray Media Lisa Conrad 63 -- Afterword: Propositions on the Organizational Form Geert Lovink and Ned Rossiter 89 -- Authors 102.
Sommario/riassunto	Digital media technologies re-pose the question of organization - and thus of power and domination, control and surveillance, disruption and emancipation. This book interrogates organization as effect and condition of media. How can we understand the recursive relationship between media and organization? How can we think, explore, critique - and perhaps alter - the organizational bodies and scripts that shape contemporary life?.

2.

Record Nr.	UNINA9910830592903321
Autore	Kao Imin
Titolo	Wafer manufacturing : shaping of single crystal silicon wafers / / Imin Kao, Chunhui Chung
Pubbl/distr/stampa	Hoboken, New Jersey : , : John Wiley & Sons, Incorporated, , [2021] Â©2021
ISBN	1-118-69625-5 1-118-69623-9 1-118-69622-0
Edizione	[First edition.]
Descrizione fisica	1 online resource (307 pages) : illustrations
Disciplina	621.38152
Soggetti	Semiconductor wafers - Design and construction
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Includes index.
Sommario/riassunto	"A wafer (often from silicon crystals) is a thin slice of semiconducting material, upon which microcircuits are constructed by doping, etching, and deposition of various materials. Generally, they are cut from a semiconductor using a diamond saw, then polished on one or both faces. Wafer slicing is the first post crystal-growth step toward producing a polished wafer for electronic device fabrication in the semiconductor and photovoltaic (PV) industry. Advanced slicing technologies such as wiresawing are nowadays widely used in wafer production because of its ability to cut single crystalline and polycrystalline crystals with large diameter and produce wafers from thick (a few mm) to very thin sizes (300 microns)."--